



RMB1SU THRU RMB10SU

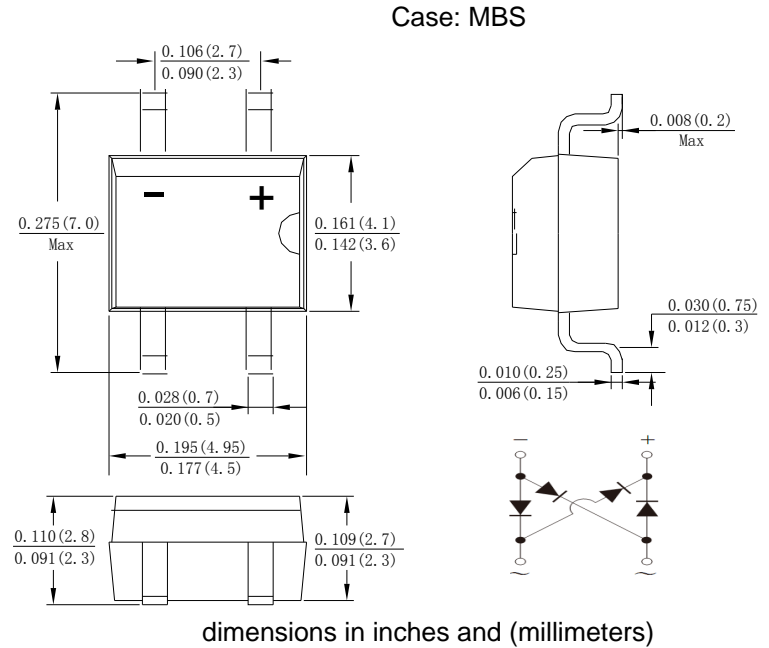
Single Phase 1.0AMP Fast Glass Passivated Bridge Rectifier

Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-35A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	RMB1SU	RMB2SU	RMB4SU	RMB6SU	RMB8SU	RMB10SU	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM}	100	200	400	600	800	1000	V
	V _{RWM}							
	V _{DC}							
RMS Reverse Voltage	V _{RMS}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T _C =100°C	I _{F(AV)}	1.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	35						A
I ² t Rating for Fusing (t < 8.3ms)	I ² t	5.084						A ² s
Forward Voltage per element @IF=1.0A	V _{FM}	1.3						V
Peak Reverse Current @T _J =25°C At Rated DC Blocking Voltage @T _J =125°C	I _R	5.0 100						uA
Maximum reverse recovery time (Note 2)	T _{RR}	150			250	500		ns
Typical Junction Capacitance (Note 3)	C _J	15						pF
Typical Thermal Resistance	R _{θJA}	60						°C/W
	R _{θJL}	16						
Operating and Storage Temperature Range	T _J ,T _{STG}	-55to+150						°C

Note:1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.

2. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.



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Fig. 1 Output Current Derating Curve

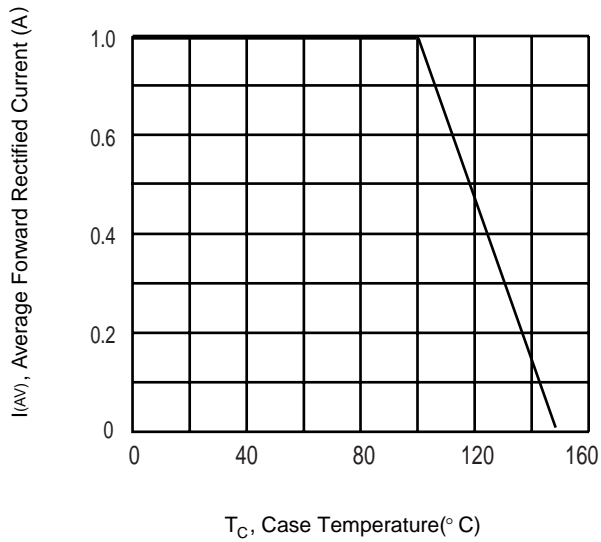


Fig. 2 Typical Forward Characteristics

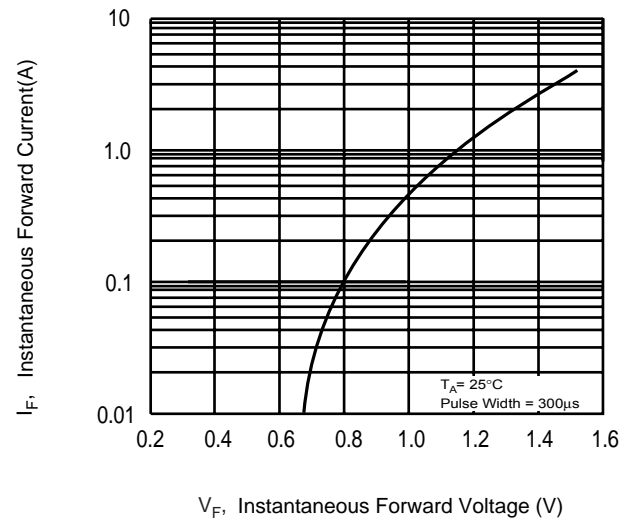


Fig.3 Maximum Peak Forward Surge Current

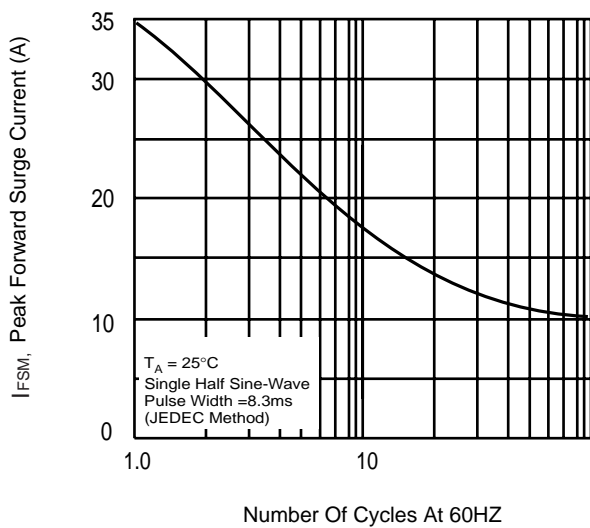


Fig. 4 Typical Junction Capacitance

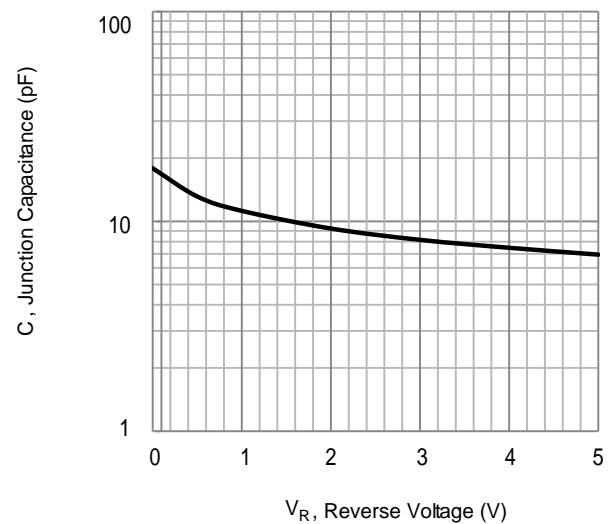


Fig.5 Typical Reverse Characteristics

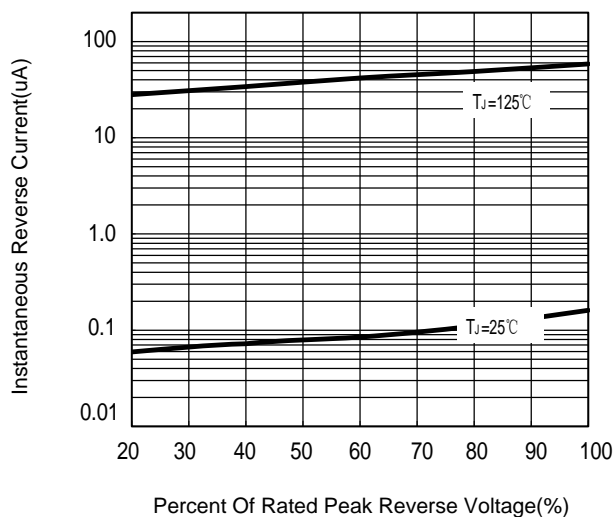
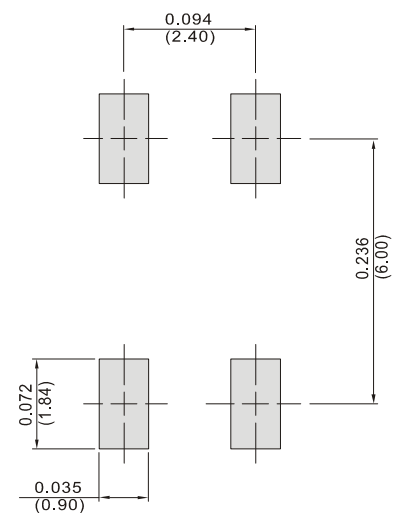


Fig.6 Mounting Pad Layout





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